

II. SPECIFICATION AMENDMENTS

Please replace the paragraph/section beginning on page 3, line 10, through page 3, line 25 as rewritten below:

FIG. 2 is an exploded view of a semiconductor cassette reducer 20 in accordance with one embodiment of the invention. The semiconductor cassette reducer 20 has a first substantially U-shaped plate 22 and a second substantially U-shaped plate 24. A plurality of wafer supports 26, 28, 30, 32 connect the first substantially U-shaped plate 22 longitudinally to the second substantially U-shaped plate 24 as shown in Fig. 3. In one embodiment screws 34 and washers 36 are used to attach the U-shaped plates 22, 24 to the wafer supports 26, 28, 30, 32. Retention springs (plurality of retention springs, more than two retention springs, flexible disks) 38 are attached to the first U-shaped plate 22 and the second U-shaped plate 24. In one embodiment, the retention springs 38 are attached using screws 40. In one embodiment, the retention springs are formed of a rubbery substance that is deformable. When the cassette reducer is placed in the FOUP the retention springs 38 (which as shown in Fig. 3 project laterally from peripheral edges of plates 22, 24) grab the sides of the FOUP. The back two retention springs 38' lock into a depression (lip) 38L in the FOUP. This provides a solid grip for the cassette in FOUP. The